Supporting Information

A strategy to fabricate lightweight multifunctional microwave absorbing composite with load-bearing and infrared stealth by modified 3D integrated hollow E-glass fiber

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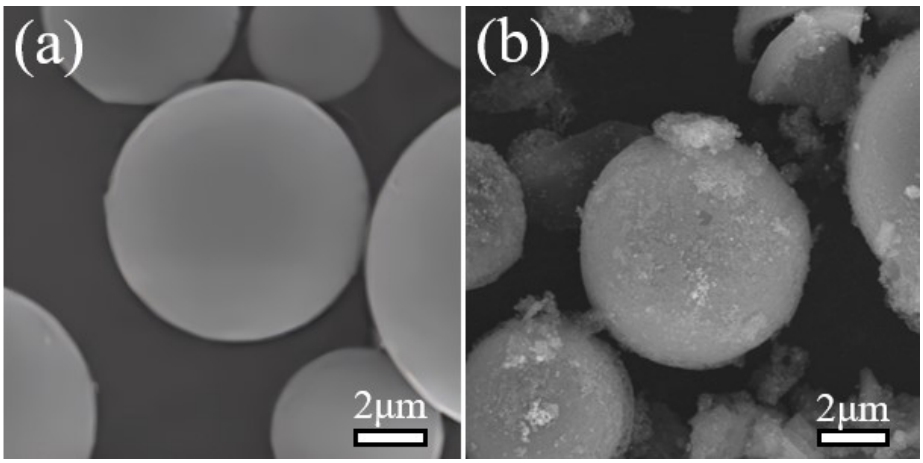

Fig. S1. Microscopic morphology of HGM (a) and HGM@Ni (b).

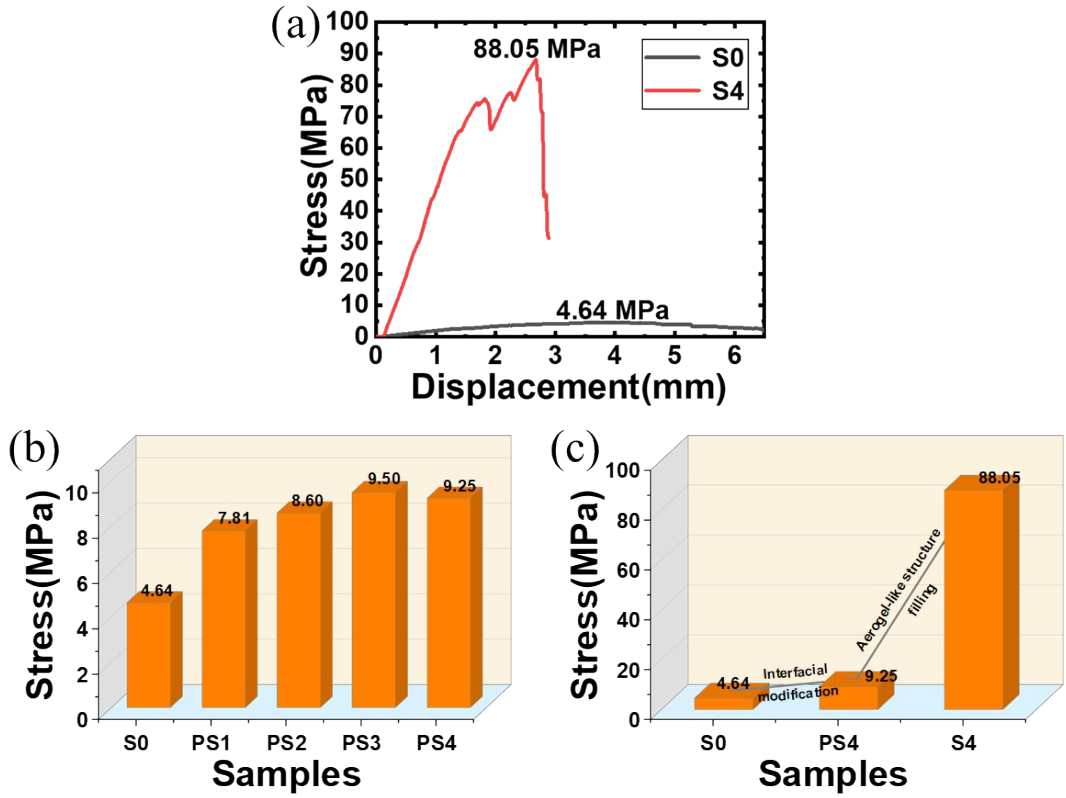

Fig. S2. (a) Flexural stress-strain curves of S0 and SFMC(S4). Flexural strength bar graph of (b) raw (S0) and modified E-glass fiber (PS1, PS2, PS3, and PS4); (c) S0 and S4.

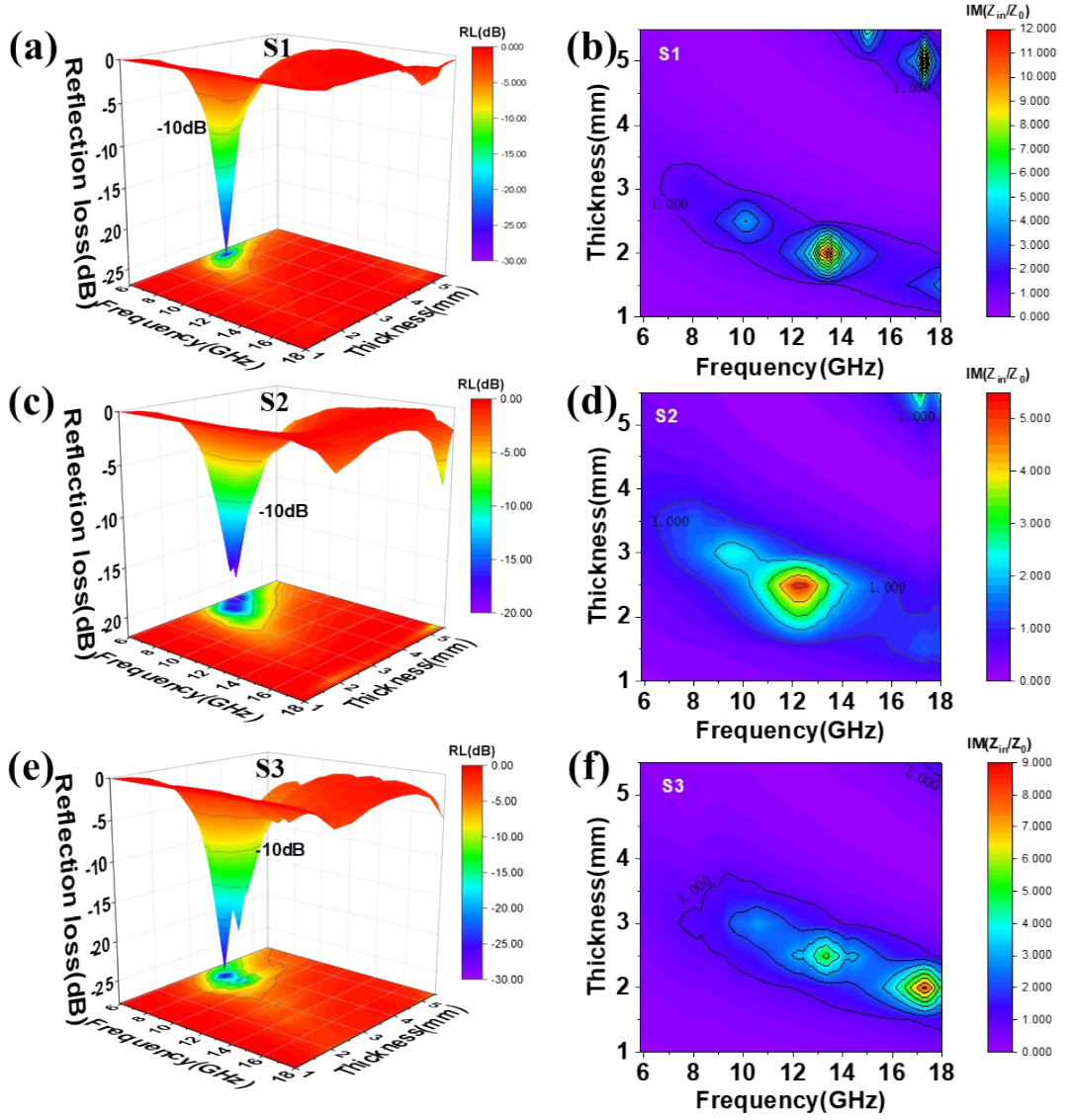

Fig. S3. (a, c, and e) 3D RL of the EMW attenuation of S1, S2, and S3. (b, d, and f) 2D impedance matching projection mappings of S1, S2, and S3.

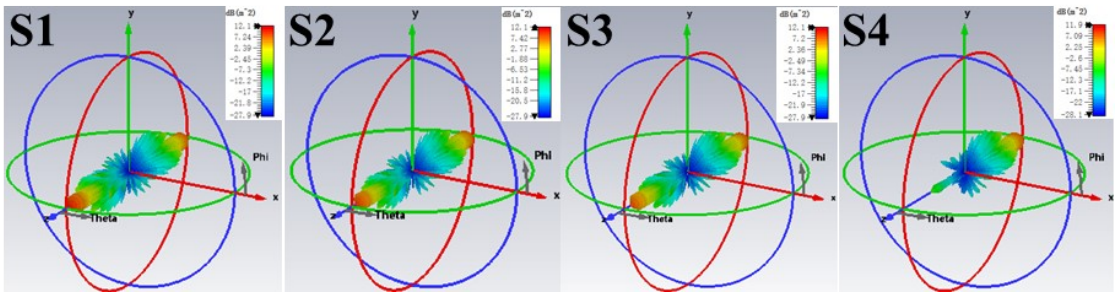

Fig. S4. RCS simulated model: the 3D spherical coordinates of samples in different directions.